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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Mostafazadeh, Shahram; Smith, Joseph O.

Assignee: National Semiconductor Corp.

Title: LEAD FRAME DESIGN FOR INCREASED CHIP PINOUT

Serial No.: 09/054,380 Filed: 04/02/98

Examiner: H. Duong Group Art Unit: 2822

Docket No.: NS-3856 US

San Jose, California  
July 8, 1999

BOX  
ASSISTANT COMMISSIONER FOR PATENTS  
Washington, D. C. 20231

**AMENDMENT**

Dear Sir:

In response to the Office Action of January 21, 1999, Applicants amend the above-referenced patent application as follows:

**IN THE CLAIMS**

Please cancel Claim 10.

In Claim 2, at line 1, please delete "1" and substitute --11--.

Please amend Claims 1, 5 and 9 as follows:

1. (amended) [In an] An integrated circuit package comprising,

(a) a lead frame comprising:

a die attach platform; and

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